

Willkommen zum (nicht ganz so praktischen) Praktikum B2.2:

## Überstruktur in $\text{Cu}_3\text{Au}$

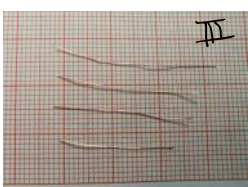
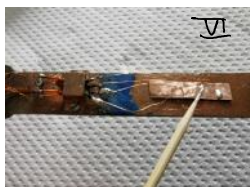
### Teil I: Das resistive Verfahren



|        | Länge [mm]   | Breite [mm]  | Dicke [mm]   |
|--------|--------------|--------------|--------------|
| Probe1 | 6.7 +/- 0.05 | 5.1 +/- 0.05 | 0.2 +/- 0.05 |
| Probe2 | 4.3 +/- 0.05 | 5.2 +/- 0.05 | 0.2 +/- 0.05 |
| Probe3 | 4.1 +/- 0.05 | 5.1 +/- 0.05 | 0.2 +/- 0.05 |

### Probenkontaktierung

(Bringe die Bilder in die richtige Reihenfolge)

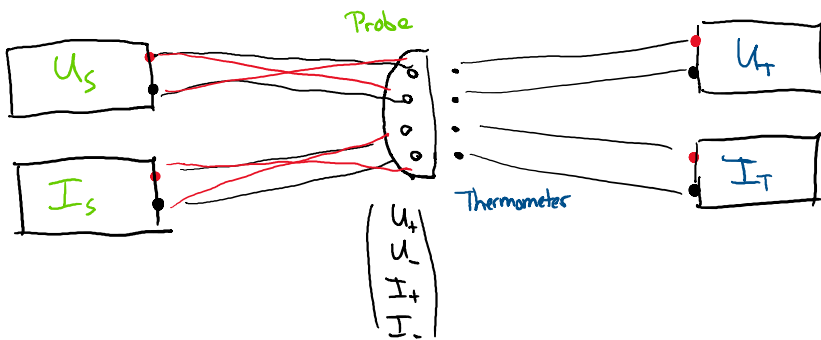
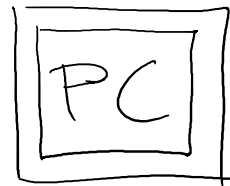


### Verkabelung



$I_T$   
 $U_S$   
 $U_T$   
 $I_S$

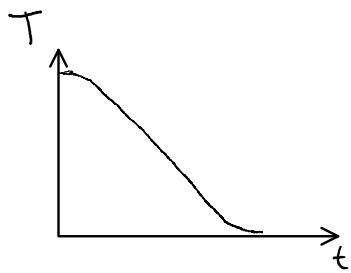
# Schaltplan



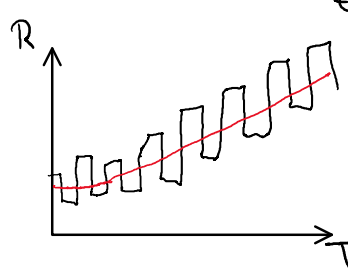
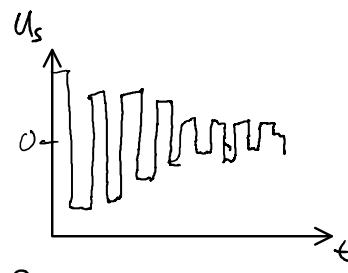
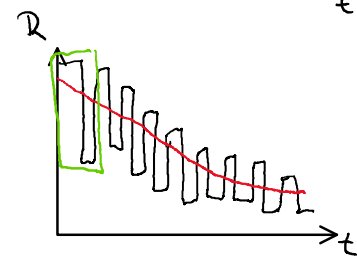
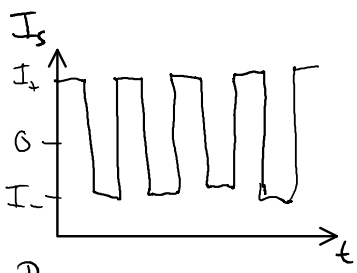
# Einbau



### Messung



$$\xi = R \cdot \frac{A}{l}$$



### Teil II: Das röntgenographische Verfahren

